

SID

Factory: Rot am See

Article:

ML8

Provided:

Customer:

Date:

24.04.2026

WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-009my 330x490mm	50201012	9	VS	1		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		2		
		35	L2			
C-RS-FR4-ML-0.107mm-035+035-TG150-HF-...	50203003	107		3	A01	
		35	L3			
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		4		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		5		
		35	L4			
C-RS-FR4-ML-0.107mm-035+035-TG150-HF-...	50203003	107		6	A02	B00
		35	L5			
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		7		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		8		
		35	L6			
C-RS-FR4-ML-0.107mm-035+035-TG150-HF-...	50203003	107		9	A03	
		35	L7			
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		10		
A-RS Kupferfolie-009my 330x490mm	50201012	9	RS	11		

Thickness after Pressing

B00:

890 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

990 µm

Dmin:

790 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1000 µm

Tol+:

100 µm

Tol-:

100 µm

Dmax:

1100 µm

Dmin:

900 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

921 µm

Version 1.2.20.35

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